

Y-C17-DEV Datasheet

Product introduction

Y-C17-DEV is based on the Plink AI development system driven by Jetson Xavier NX、ORIN NX and ORIN NANO modules. All the components on the board are of wide temperature type, the main interface is designed for electrostatic safety protection, and the power supply application scheme of high reliability is adopted. The input power supply has the functions of overvoltage and reverse polarity protection, and has a variety of external interfaces. It can also carry hundreds of functional modules through a MiniPCIe connector (including USB2.0 and PCIe X1 signals) to achieve further expansion of system functions. The M.2 B key slot of the Y-C17 carrier board can directly carry 4G/5G communication modules, and the carrier board has a Nano SIM card slot.

Product feature

- 2 x Type-C connector
- 1 x Nano type SIM card connector
- 1 x full length MiniPCIe connector
- 1 x M.2 2230 M key slot
- 1 x M.2 3050 B key slot (Expandable 4G/5G communication module)
- 1 x 2 Lane MIPI camera interface FPC connector
- 1 x 3.3V RTC power supply port
- 1 x Fan control interface (5V)
- Automatic power on
- Anti-shedding power supply terminals
- Board size: 85mm * 63mm * 35mm
- Power input: DC +12V ~ +24V
- Working temperature: -25 ~ +65°C
- Weight: 125g



Order model	Description	Heat dissipation mode
Y-C17-DEV	Inside Jetson Xavier NX、ORIN NX、ORIN NANO module	Active